

Dual N-Channel Enhancement Mode MOSFET

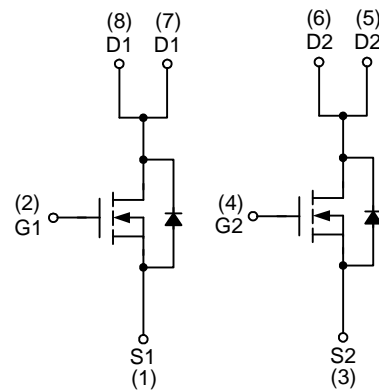
### Features

- 60V/6A,  
 $R_{DS(ON)} = 38m\Omega$  (Typ.) @  $V_{GS} = 10V$   
 $R_{DS(ON)} = 55m\Omega$  (Typ.) @  $V_{GS} = 4.5V$
- Super High Dense Cell Design
- Reliable and Rugged
- Lead Free and Green Devices Available  
 (RoHS Compliant)

### Pin Description



Top View of DIP-8



N-Channel MOSFET

### Applications

- Power Management in DC/DC Converter,  
 DC/AC Inverter Systems

### Ordering and Marking Information

<p>APM9946 <span style="font-family: monospace;">□□-□□□</span></p> <div style="margin-left: 20px;"> <p>└─ Assembly Material</p> <p>└─ Handling Code</p> <p>└─ Temperature Range</p> <p>└─ Package Code</p> </div>	<p>Package Code                  J : DIP-8</p> <p>Operating Junction Temperature Range                  C : -55 to 150 °C</p> <p>Handling Code                  TU : Tube</p> <p>Assembly Material                  G : Halogen and Lead Free Device</p>
<p>APM9946 J : <span style="border: 1px solid black; padding: 2px; display: inline-block; text-align: center;">                       APM9946                      XXXXX                 </span></p>	<p>XXXXX - Date Code</p>

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020C for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter		Rating	Unit
$V_{DSS}$	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	
$I_D^*$	Continuous Drain Current	$V_{GS}=10V$	6	A
$I_{DM}^*$	Pulsed Drain Current		20	
$I_S^*$	Diode Continuous Forward Current		3	A
$T_J$	Maximum Junction Temperature		150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55 to 150	
$P_D^*$	Power Dissipation	$T_A=25^\circ\text{C}$	2.5	W
		$T_A=100^\circ\text{C}$	1	
$R_{\theta JA}^*$	Thermal Resistance-Junction to Ambient		50	$^\circ\text{C/W}$

Note : \*Surface Mounted on  $1\text{in}^2$  pad area,  $t \leq 10$  sec.

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	APM9946J			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu\text{A}$	60	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=48V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	1	$\mu\text{A}$
			-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	1	2	3	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^a$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=6A$	-	38	55	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=4A$	-	55	77	
$V_{SD}^a$	Diode Forward Voltage	$I_{SD}=3A, V_{GS}=0V$	-	0.8	1.1	V
<b>Gate Charge Characteristics<sup>b</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=30V, V_{GS}=10V,$ $I_{DS}=6A$	-	19.1	27	nC
$Q_{gs}$	Gate-Source Charge		-	3.7	-	
$Q_{gd}$	Gate-Drain Charge		-	4.9	-	

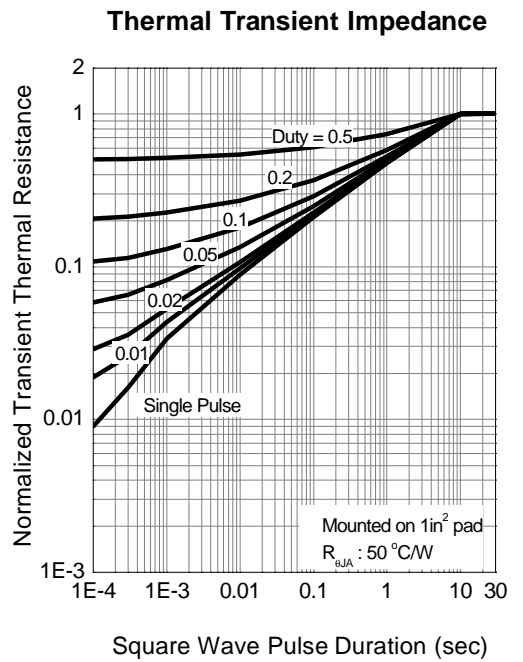
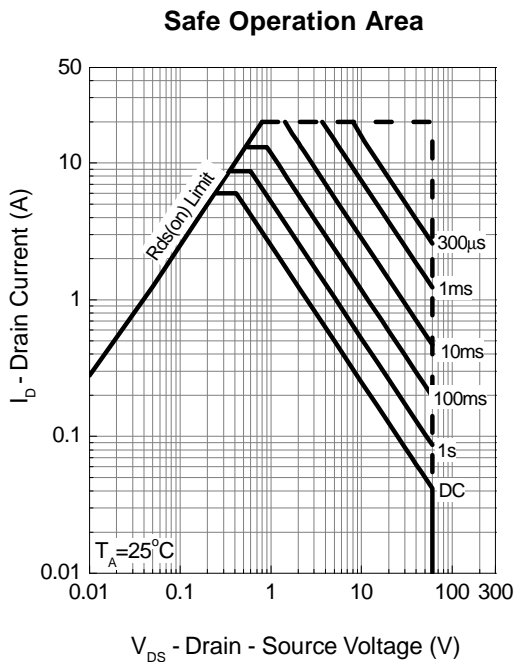
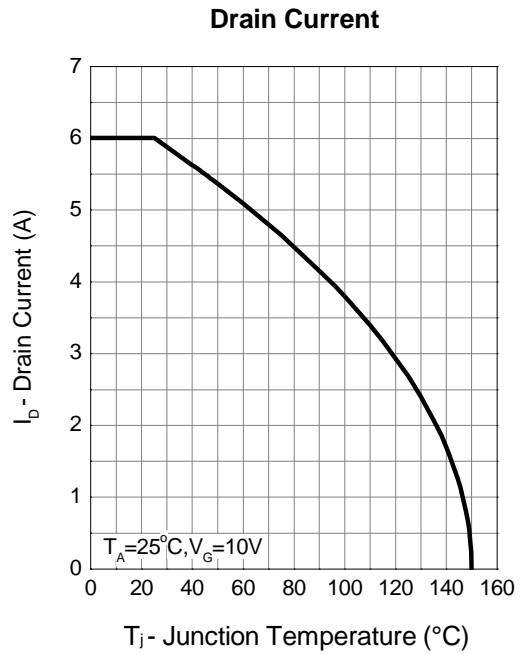
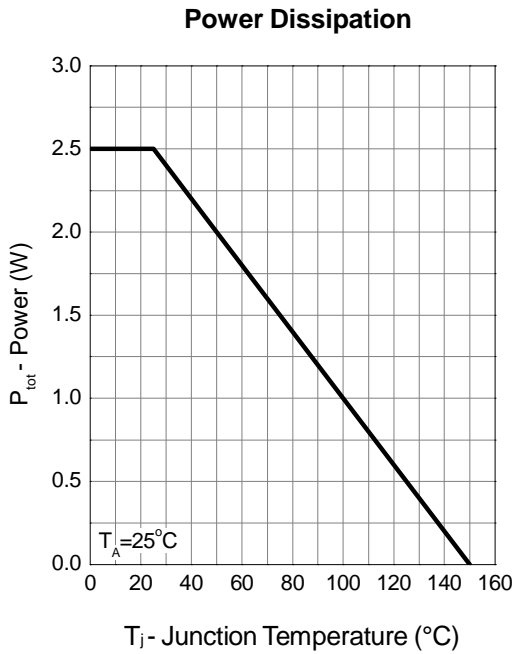
**Electrical Characteristics (Cont.)** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	APM9946J			Unit
			Min.	Typ.	Max.	
<b>Dynamic Characteristics<sup>b</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	1	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=30V,$ Frequency=1.0MHz	-	950	-	pF
$C_{oss}$	Output Capacitance		-	70	-	
$C_{rss}$	Reverse Transfer Capacitance		-	50	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=30V, R_L=30\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	8	15	ns
$T_r$	Turn-on Rise Time		-	7	14	
$t_{d(OFF)}$	Turn-off Delay Time		-	25	46	
$T_f$	Turn-off Fall Time		-	5	10	
$t_{rr}$	Reverse Recovery Time	$I_{SD}=6A, di_{SD}/dt=100A/\mu s$	-	24	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	26	-	nC

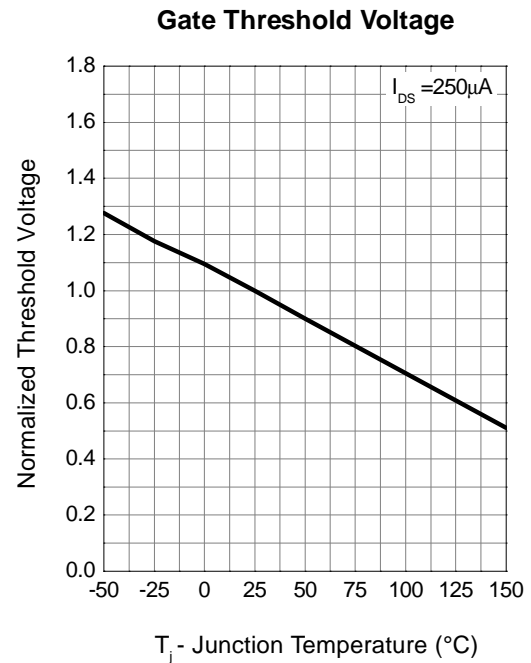
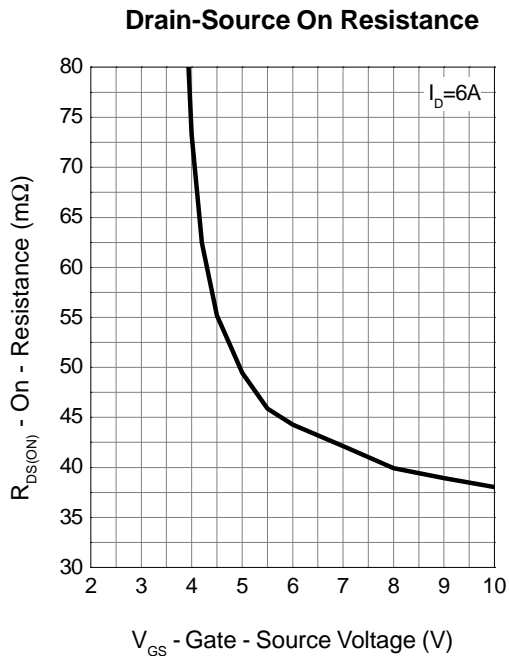
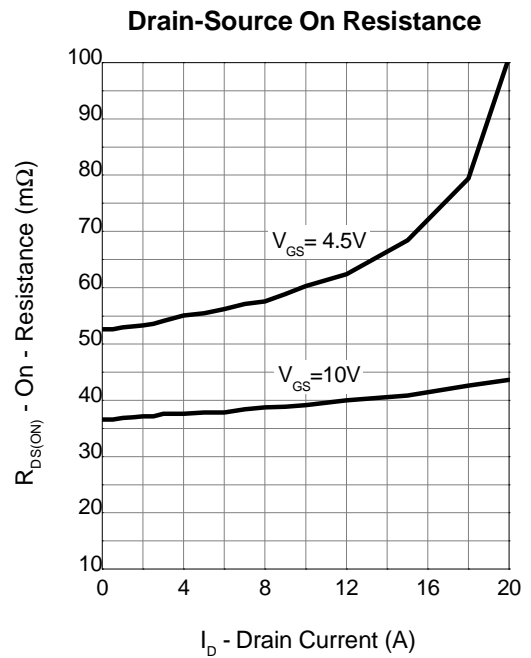
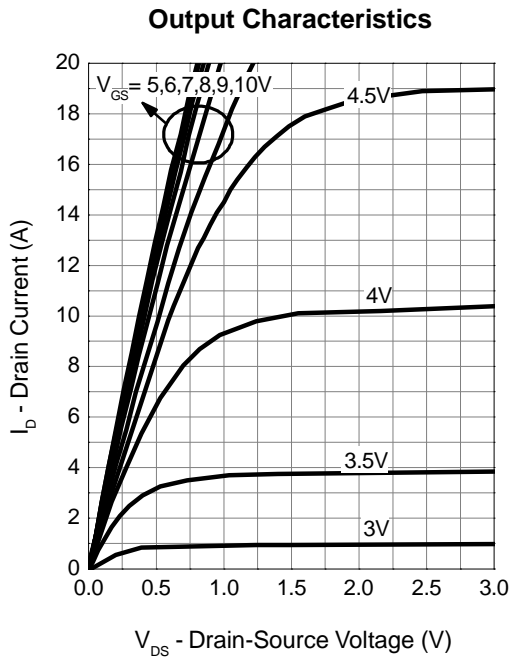
Note a : Pulse test ; pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

Note b : Guaranteed by design, not subject to production testing.

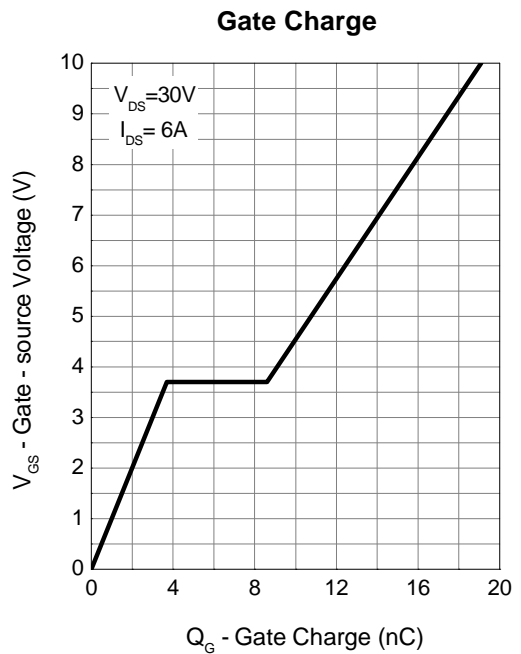
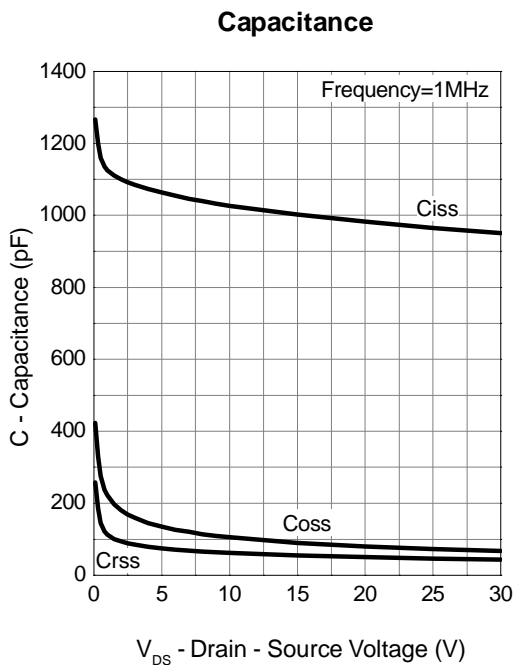
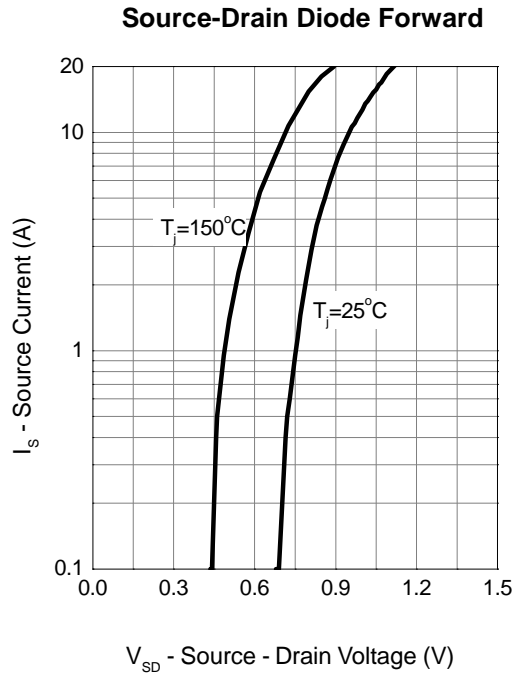
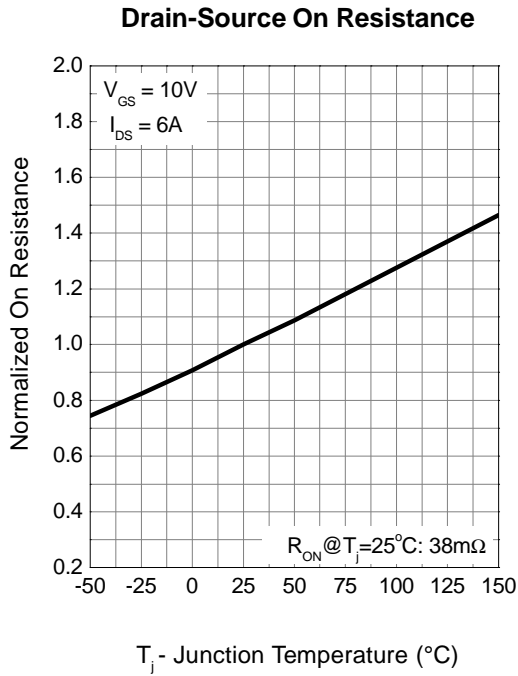
### Typical Operating Characteristics



Typical Operating Characteristics (Cont.)

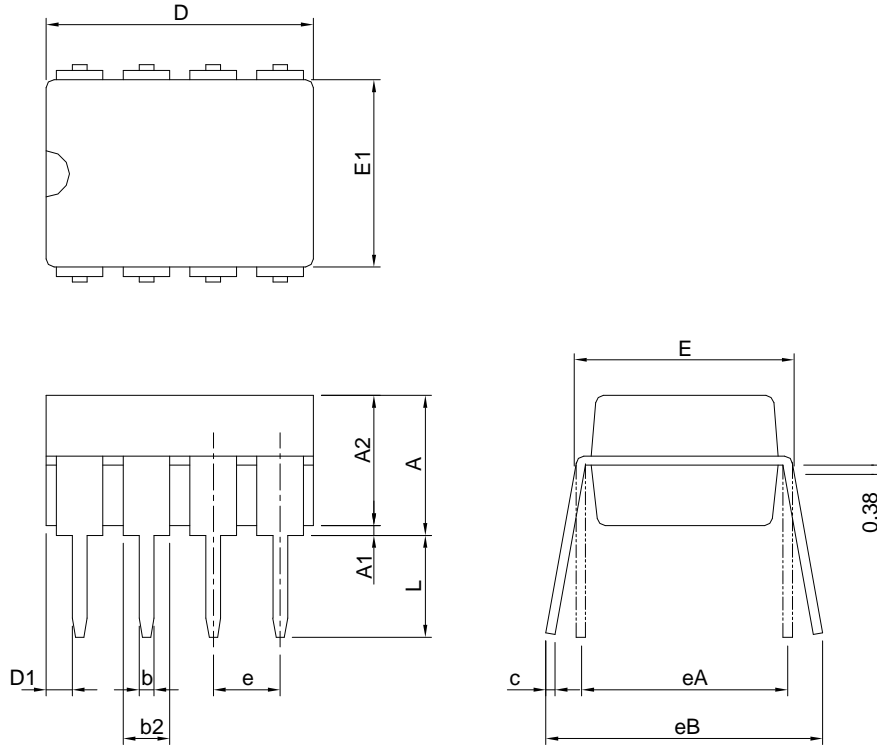


Typical Operating Characteristics (Cont.)



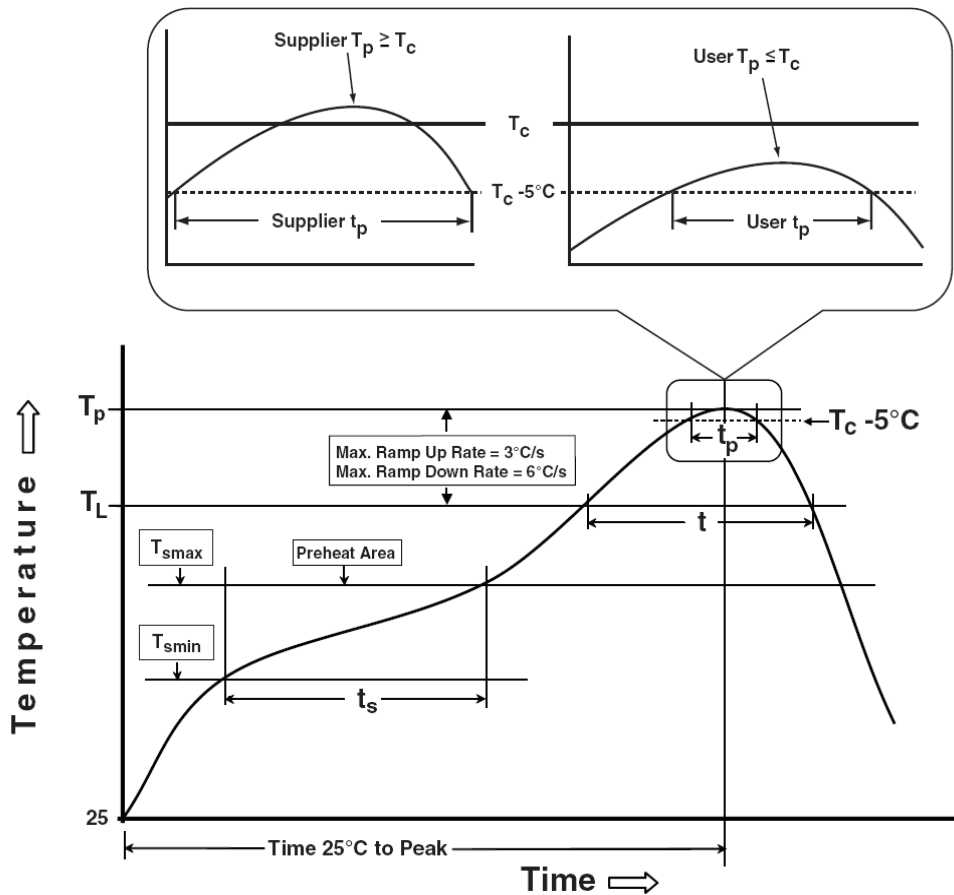
## Package Information

DIP-8



SYMBOL	DIP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		5.33		0.210
A1	0.38		0.015	
A2	2.92	4.95	0.115	0.195
b	0.36	0.56	0.014	0.022
b2	1.14	1.78	0.045	0.070
c	0.20	0.35	0.008	0.014
D	9.01	10.16	0.355	0.400
D1	0.13		0.005	
E	7.62	8.26	0.300	0.325
E1	6.10	7.11	0.240	0.280
e	2.54 BSC		0.100 BSC	
eA	7.62 BSC		0.300 BSC	
eB		10.92		0.430
L	2.92	3.81	0.115	0.150

### Classification Profile



### Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_l$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within $5^\circ\text{C}$ of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time $25^\circ\text{C}$ to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.  
 \*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.



## Classification Reflow Profiles (Cont.)

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HOLT	JESD-22, A108	1000 Hrs, Bias @ 125°C
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

## Customer Service

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